

# **General Description**

This single 2-input positive- OR gate is designed for 1.65-V to 5.5-V  $V_{CC}$  operation. The SN74LVC1G32 performs the Boolean function. Y=A+B or Y= $\overline{\overline{A} \cdot \overline{B}}$  .in positive logic. The CMOS device has high output drive while maintaining low static power dissipation over a broad  $V_{CC}$  operating range.

This SN74LVC1G32

#### **Features**

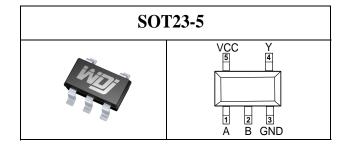
- Operate from 1.65 V to 5.5 V
- Supports 5-V VCC operation
- Specified from -40°C to 125°C

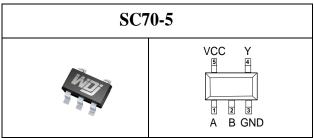
- Provides down translation to V<sub>CC</sub>
- Max  $t_{pd}$  of 3.8 ns at 3.3 V
- ±24-mA output drive at 3.3 V

# **Applications**

- Personal navigation device (GPS)
- AV receiver
- High-speed data acquisition and generation
- SSD: internal and external
- Digital picture frame (DPF)
- TV: LCD/digital and high-definition (HDTV)

# **Pinning and Package**





# **Order information**

Package	Orderable Device	Packing Option
SOT23-5	SN74LVC1G32DBVRW	- 3000/盘
SC70-5	SN74LVC1G32DCKRW	3000/盛

# **Functional Block Diagram**





# **Pin Functions**

	Pin	Tuno	Description
Name	SOT23-5/SC70-5	Туре	Description
Α	1	I	Data Input
В	2	l	Data Input
GND	3	-	Ground
Υ	4	0	Data Output
Vcc	5	-	Supply Voltage

# **Absolute Maximum Ratings**

	Parameter	Min	Max.	Unit	
Vcc	Supply volt	age range	-0.5	6.5	V
VI	Input volta	ige range	-0.5	6.5	V
Vo	Voltage range applied to any output in	the high-impedance or power-off state	-0.5	6.5	V
Vo	Voltage range applied to any	-0.5	V <sub>CC</sub> +0.5	V	
Iĸ	Input clamp current V<0			-50	mA
Іок	Output clamp current	Vo<0		-50	mA
lo	Continuous o	utput current		±50	mA
	Continuous current throu	igh Vcc or GND		±100	mA
TJ	Junction tempera	-55	150	°C	
T <sub>stg</sub>	Storage temp	erature range	-55	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# **ESD Ratings**

	E	Value	Unit	
\//ECD\	Human-Body Model (HBM) <sup>(1)</sup>		8 K	V
V(ESD) Electrostatic Discharge	Charged-Device Model (CDM)(2)	1.5K	V	

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

### Thermal Information

Package Type	<b>Ө</b> ЈА	θις	Unit
SOT23-5	250	81	°C/W
SC70-5	400	150	°C/W

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



# **Recommended Operating Conditions**

Over operating free-air temperature range (unless otherwise noted)

Symbol	Pa	arameter	Min	Max	Unit	
Vcc	Supply Voltage	Operating	1.65	5.5	V	
		V <sub>CC</sub> =1.65V to 1.95V	0.65×V <sub>CC</sub>			
.,		V <sub>CC</sub> =2.3V to 2.7V	1.7		1 .,	
V <sub>IH</sub>	High-Level Input Voltage	V <sub>CC</sub> =3V to 3.6V	2		\ \ \ \	
		V <sub>CC</sub> =4.5V to 5.5V	0.7×V <sub>CC</sub>		1	
		V <sub>CC</sub> =1.65V to 1.95V		0.35×V <sub>cc</sub>		
	Lave Lavel Immed Valtage	V <sub>CC</sub> =2.3V to 2.7V		0.7		
$V_{IL}$	Low-Level Input Voltage	V <sub>CC</sub> =3V to 3.6V		0.8	\  \ \ \	
		V <sub>CC</sub> =4.5V to 5.5V		0.3×V <sub>CC</sub>	1	
Vı	In	put Voltage	0	5.5	V	
Vo	Ou	Output Voltage				
	High-Level Output Current	V <sub>CC</sub> =1.65V		-4		
		Vcc=2.3V		-8		
Іон		N/ 01/		-16	m/	
		V <sub>CC</sub> =3V		-24		
		V <sub>CC</sub> =4.5V		-32		
		V <sub>CC</sub> =1.65V		4		
		V <sub>CC</sub> =2.3V		8	1	
I <sub>OL</sub>	Low-Level Output Current			16	m/	
		V <sub>CC</sub> =3V		24		
		V <sub>CC</sub> =4.5V		32		
		V <sub>CC</sub> =1.8V±0.15V, 2.5V±0.2V		20		
Δt/Δν	Input Transition Rise or Fall Rate	V <sub>CC</sub> =3.3V±0.3V		10	ns/V	
		V <sub>CC</sub> =5V±0.5V		5		
TA	Operating Free-air Temperature	All Other Packages	-40	125	°C	

<sup>(1)</sup> All unused digital inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.



# **Electrical Characteristics**

V<sub>CC</sub>=1.65V to 5.5V, FULL=–40°C to +125°C. Typical values are at TA=+25°C (unless otherwise noted)

Parameter	Symbol	Test Conditions	Vcc	TA	Min	Тур	Max	Units
		Output						
		I <sub>OH</sub> =–100μA	1.65V to 5.5V	FULL	Vcc-0.1			V
		I <sub>OH</sub> =–4mA	1.65V	FULL	1.2			V
		I <sub>OH</sub> =8mA	2.3V	FULL	1.9			V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> =–16mA		FULL	2.4			V
		I <sub>OH</sub> =–24mA	3V	FULL	2.3			V
		I <sub>ОН</sub> =-32mА	4.5V	FULL	3.8			V
		I <sub>OL</sub> =100μA	1.65V to 5.5V	FULL			0.1	V
	VoL	I <sub>OL</sub> =4mA	1.65V	FULL			0.45	V
		I <sub>OL</sub> =8mA	2.3V	FULL			0.3	V
Output Low Voltage		I <sub>OL</sub> =16mA		FULL			0.4	V
		I <sub>OL</sub> =24mA	3V	FULL			0.65	V
		I <sub>OL</sub> =32mA	4.5V	FULL			0.65	V
Off-State Current	l <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> =5.5V	0V	FULL			±25	μA
		Input						
Input Leakage Current	l <sub>l</sub>	V <sub>i</sub> =5.5V or GND	0V to 5.5V	FULL			±5	μA
Input Capacitance	Cı	V <sub>I</sub> =V <sub>CC</sub> or GND	3.3V	FULL		4		pF
		Power Supply	,					
Power Supply Range	V <sub>CC</sub>		1.65V to 5.5V	FULL	1.65		5.5	V
Power Supply Current	Icc	V <sub>I</sub> =V <sub>CC</sub> or GND, I <sub>O</sub> =0	5.5V	FULL			10	μΑ
Delta Power Current	Δl <sub>CC</sub>	One Input at V <sub>CC</sub> – 0.6V, Other Inputs at V <sub>CC</sub> or GND	3V to 5.5V	FULL			500	μA

<sup>(1)</sup> All unused digital inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.

Switching Characteristics Over recommended operating free-air temperature range,  $C_L$ =30pF or 50 pF (unless otherwise noted)

		-40°C to +125°C											
Parameter	From(Input)	To(Output)	V <sub>CC</sub> =1.8V±0.15		V <sub>CC</sub> =1.8V±0.15V V <sub>C</sub>		V <sub>CC</sub> =2.5V±0.2V V <sub>CC</sub>		V <sub>CC</sub> =3.3V±0.3V		V <sub>cc</sub> =5V±0.5V		Units
			Min	Max	Min	Max	Min	Max	Min	Max			
t <sub>pd</sub>	A or B	Y	1	9	1	3.8	1	3.8	1	3.3	ns		

# **Operating Characteristics**

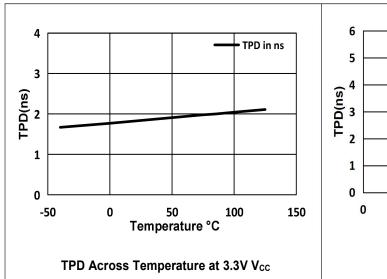
TA=-40°C to +125°C

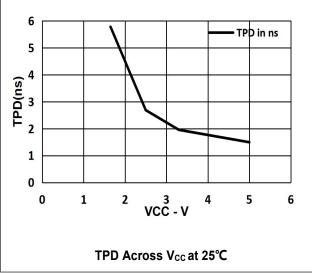
	Parameter		Test	V <sub>cc</sub> =1.8V	V <sub>cc</sub> =2.5V	V <sub>cc</sub> =3.3V	V <sub>cc</sub> =5V	Units
			Conditions	Тур	Тур	Тур	Тур	Ullits
	C <sub>pd</sub>	Power Dissipation Capacitance	f=10Mhz	23	23	23	29	pF



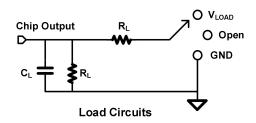
# **Typical Characteristics**

V<sub>CC</sub>=1.65V or 5.5V, FULL=–40°C to +125°C. Typical values are at TA=+25°C (unless otherwise noted)





# **Parameter Measurement Information**

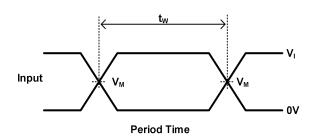


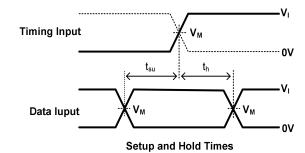
TEST	S1
Трнь/Трьн	OPEN
T <sub>PLZ</sub> /T <sub>PZL</sub>	$V_{LOAD}$
T <sub>PHZ</sub> /T <sub>PZH</sub>	GND

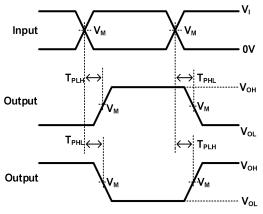
Vcc	INP	UTS	V <sub>M</sub>	V <sub>LOAD</sub>	C∟	R∟	VΔ
VCC	Vı	T <sub>f</sub> /T <sub>f</sub>	VWI	<b>▼</b> LOAD	OL	IV.	VΔ
1.8V±0.15V	Vcc	≤2ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30pF	500Ω	0.15V
2.5V±0.15V	Vcc	≤2ns	Vcc/2	2×V <sub>CC</sub>	30pF	500Ω	0.15V
3.3V±0.15V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.15V	Vcc	≤2.5ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	50pF	500Ω	0.3V



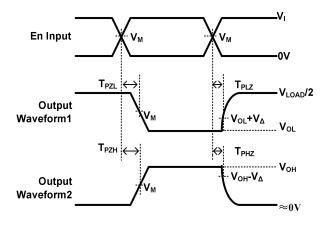
# **Parameter Measurement Information (Continued)**







Propagation Delay for Output and Inverted Output



**Enable and Disable Times** Low-And High-Level Enabling

Notes:A. C<sub>L</sub> includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the F. tPZL and tPZH are the same as ten. output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR 10 MHz, Z =50.

- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{\text{PLZ}}$  and  $t_{\text{PHZ}}$  are the same as  $t_{\text{dis}}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd.}$
- H. All parameters and waveforms are not applicable to all device.

# **Detailed Description**

### Overview

The GT74LVC1G32 device contains one 2-input positive OR gate device and performs the Boolean function Y = A + B or  $Y = \overline{A} \cdot \overline{B}$ . This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The loff feature allows voltages on the inputs and outputs, when V<sub>CC</sub> is 0 V.

# **Functional Block Diagram**





### **Feature Description**

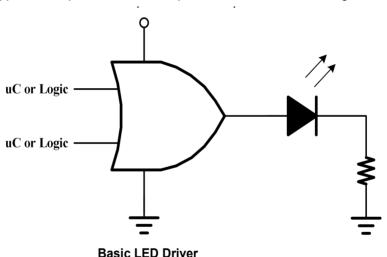
- Wide operating voltage range.
- Operates from 1.65 V to 5.5 V.
- Allows down voltage translation.
- Inputs accept voltages to 5.5 V.
- loff feature allows voltages on the inputs and outputs, when Vcc is 0 V.

#### **Device Functional Modes**

Inpu	its	Output
Α	В	Y
Н	X	Н
X	Н	Н
L	L	L

# **Application Note**

The GT74LVC1G32 is a high drive CMOS device that can be used for implement OR logic with a high output drive, such as an LED application. It can produce 24-mA of drive current at 3.3V making it Ideal for driving multiple outputs and good for high speed applications up to 100Mhz. The inputs are 5.5-V tolerant allowing translation down to Vcc

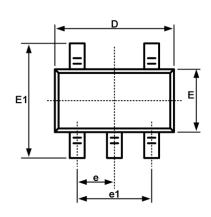


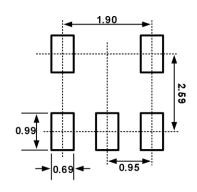
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- $\mu$ F capacitor is recommended. If there are multiple VCC pins, then a 0.01- $\mu$ F or 0.022- $\mu$ F capacitor is recommended for each power pin. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

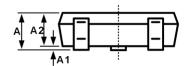


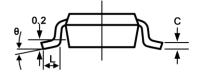
# Package Outline SOT23-5





Recommended Land Pattern (Unit: mm)

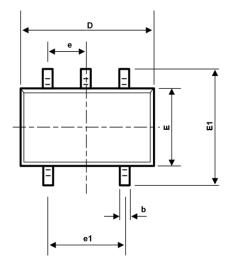


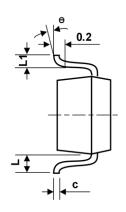


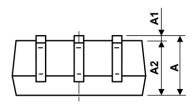
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950BSC		0.037BSC	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
L1	0.600REF		0.024REF	
θ	0°	8°	0°	8°



# Package Outline SC70-5







symbol	Dimension In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
Α	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
С	0.110	0.175	0.004	0.007
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
е	0.650TYP		0.026TYP	
e1	1.200	1.400	0.047	0.055
L	0.525REF		0.021REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°



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